

# 10Gb/s XFP 20km BIDI Tx1330/Rx1270 Optical Transceiver

#### **Product Features**

- Supports 8.0Gb/s to 11.1Gb/s bit rates
- Hot-pluggable XFP footprint, Built-in digital diagnos
- Maximum link length of 20km with SMF
- 1330nm DFB laser and PIN photodiode
- XFP MSA package with duplex LC connector
- No reference clock required
- Single +3.3V power supply
- Power dissipation <1.5W</li>
- Compatible with RoHS
- Temperature range : -5 to +85 $^{\circ}$  C

#### **Applications**

- SONET OC-192&SDH STM-64 at 9.953Gbps
- 10GBASE-LR/LW 10G Ethernet
- 1200-SM-LL-L 10G Fibre Channel
- 10GE over G.709 at 11.09Gbps
- OC192 over FEC at 10.709Gbps
- Other optical links, up to 11.1Gbps

This product is compliant with the 10G Small Form-Factor Pluggable (XFP) Multi-Source Agreement (MSA), supporting data-rate of 8.0~11.1Gbps, and transmission distance up to 20km on SMF.

The transceiver module comprises a transmitter with 1330nm DFB laser and a receiver with a PIN photodiode. Transmitter and receiver are separate within a wide temperature range and offers optimum heat dissipation and excellent electromagnetic shielding thus enabling high port densities for 10 GbE systems.

#### **Ordering Information**

Part Number	Description
AC-B-XFPBI20-E32-xx	XFP 10G BIDI Tx1330nm/Rx1270nm 20km Extended Temperature Optical Transceiver

## **Regulatory Compliance**

Feature	Standard	Performance
Electromagnetic Interference (EMI)	FCC Part 15 Class B EN 55022:2010, Class B	Compatible with standards
Electromagnetic susceptibility (EMS)	EN 55024:2010	Compatible with standards
Laser Eye Safety	FDA 21CFR 1040.10 and 1040.11 EN60950, EN (IEC) 60825-1,2	Compatible with Class I laser product



#### **Absolute Maximum Ratings**

The operation in excess of any absolute maximum ratings might cause permanent damage to this module.

Parameter	Symbol	Min	Max	Unit	Notes
Storage Temperature	TS	-40	85	degC	
Power Supply Voltage	VCC	-0.5	4.5	V	
Relative Humidity (non-condensation)	RH	5	85	%	

# **Recommended Operating Conditions and Power Supply Requirements**

Parameter	Symbol	Min	Typical	Max	Unit	Notes
Operating Case Temperature	ТОР	-5		85	degC	
Power Supply Voltage	VCC	3.135	3.3	3.465	V	
Data Rate, each Lane		8.0		11.1	Gb/s	
Power Supply Current	lcc			500	mA	

## **Optical Characteristics**

Parameter		Min	Typical	Max	Unit	Notes		
Transmitter								
Wavelength	λς	1320	1330	1340	nm			
ridth (-20dB)	Δλ			1	nm			
Side-Mode Suppression Ratio		30			dB			
Average Output Power		-3		+2	dBm	1		
Extinction Ratio		3.5			dB			
Data Input Swing Differential		180		950	mV	2		
Input Differential Impedance		90	100	110	Ω			
TX Disable Disable		2.0		Vcc	V			
	Wavelength idth (-20dB) uppression Ratio Dutput Power tion Ratio wing Differential ntial Impedance	Navelength λc   idth (-20dB) Δλ   uppression Ratio SMSR   Dutput Power Pout   tion Ratio ER   wing Differential V <sub>IN</sub> ntial Impedance Z <sub>IN</sub>	Navelength   λc   1320     idth (-20dB)   Δλ   1320     uppression Ratio   SMSR   30     Dutput Power   Pout   -3     tion Ratio   ER   3.5     wing Differential   V <sub>IN</sub> 180     ntial Impedance   Z <sub>IN</sub> 90	TransmitterNavelength $\lambda c$ 13201330idth (-20dB) $\Delta \lambda$ 1uppression RatioSMSR30Dutput Power $P_{out}$ -3tion RatioER3.5wing Differential $V_{IN}$ 180ntial Impedance $Z_{IN}$ 90100	TransmitterWavelength $\lambda c$ 132013301340idth (-20dB) $\Delta \lambda$ 11uppression RatioSMSR301Output Power $P_{out}$ -3+2tion RatioER3.51wing Differential $V_{IN}$ 180950ntial Impedance $Z_{IN}$ 90100110	TransmitterNavelength $\lambda c$ 132013301340nmidth (-20dB) $\Delta \lambda$ 11nmuppression RatioSMSR301dBDutput Power $P_{out}$ -3+2dBmtion RatioER3.5dBwing Differential $V_{IN}$ 180950mVntial Impedance $Z_{IN}$ 90100110 $\Omega$		



10GBASE-BX-D XFP 20km E-Temp Specifications

Enable		0		0.8	V	
		Receiv	ver	· ·	·	
Centre Wavelength	λς	1260	1270	1280	nm	
Receiver Sensitivity				-14.5	dBm	3
Receiver Overload		0.5			dBm	3
LOS De-Assert	LOSD			-15.5	dBm	
LOS Assert	LOSA	-26			dBm	
LOS Hysteresis		0.5		4	dB	
Data Output Swing Differential	Vout	400	600	800	mV	2
1.00	High	2.0		Vcc	V	
LOS	Low			0.8	V	

### Notes:

1. The optical power is launched into SMF.

2. Internally AC-coupled.

3. Measured with a PRBS 2<sup>31</sup>-1 test pattern @9953Mbps, BER  $\,\leqslant\!1\times10^{\text{-12}}.$ 

# **Digital Diagnostic Functions**

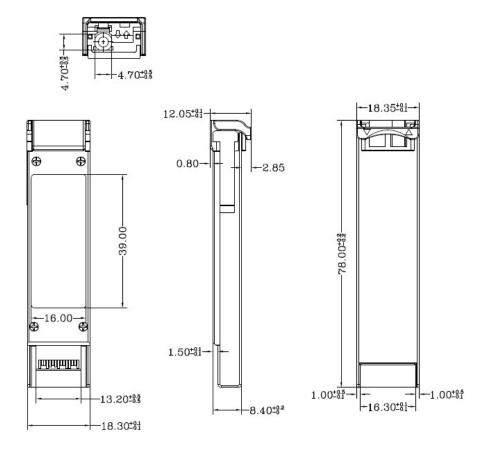
The following digital diagnostic characteristics are defined over the normal operating conditions unless otherwise specified.

Parameter	Symbol	Min	Max	Unit	Notes
Temperature monitor absolute error	DMI_Temp	-3	3	degC	Over operating temp
Supply voltage monitor absolute error	DMI_VCC	-0.1	0.1	V	Full operating range
Channel RX power monitor absolute error	DMI_RX	-3	3	dB	Per channel
Channel Bias current monitor	DMI_Ibias	-10%	10%	mA	Per channel
Channel TX power monitor absolute error	DMI_TX	-3	3	dB	Per channel



10GBASE-BX-D XFP 20km E-Temp Specifications

# **Mechanical Dimension**

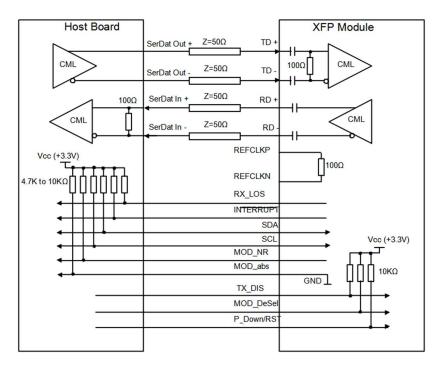


(Unit: mm [inch])

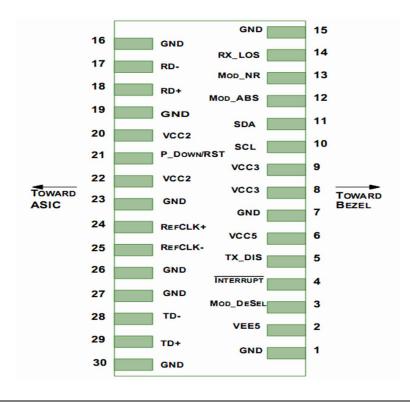


10GBASE-BX-D XFP 20km E-Temp Specifications

## **Recommended High-speed Interface Circuit**



# **Pin Assignment and Description**





10GBASE-BX-D XFP 20km E-Temp Specifications

# **Pin Assignment**

Pin	Logic	Symbol	Name/Description	Ref
1		GND	Module Ground	1
2		VEE5	Optional –5.2 Power Supply – <b>Not required</b>	
3	LVTTL-I	Mod-Desel	Module De-select; When held low allows the module to, respond to 2-wire serial	
			interface commands	
4	LVTTL-O	Interrupt	Interrupt (bar); Indicates presence of an important condition which can be read over	2
			the serial 2-wire interface	
5	LVTTL-I	TX_DIS	Transmitter Disable; Transmitter laser source turned off	
6		VCC5	+5 Power Supply – Not required	1
7		GND	Module Ground	1
8		VCC3	+3.3V Power Supply	
9		VCC3	+3.3V Power Supply	
10	LVTTL-I	SCL	Serial 2-wire interface clock	2
11	LVTTL-	SDA	Serial 2-wire interface data line	2
12	LVTTL-O	Mod_Abs	Module Absent; Indicates module is not present. Grounded in the module.	2
13	LVTTL-O	Mod_NR	Module Not Ready;	2
14	LVTTL-O	RX_LOS	Receiver Loss of Signal indicator	2
15		GND	Module Ground	1
16		GND	Module Ground	1
17	CML-O	RD-	Receiver inverted data output	
18	CML-0	RD+	Receiver non-inverted data output	
19		GND	Module Ground	1
20		VCC2	+1.8V Power Supply – Not required	
			Power Down; When high, places the module in the low power stand-by mode and on	
21	LVTTL-I	P_Down/RS	the falling edge of P_Down initiates a module reset	
		Т	Reset; The falling edge initiates a complete reset of the module including the 2-wire	
			serial interface, equivalent to a power cycle.	
22		VCC2	+1.8V Power Supply – Not required	
23		GND	Module Ground	1
24	PECL-I	RefCLK+	Reference Clock non-inverted input, AC coupled on the host board – Not required	3
25	PECL-I	RefCLK-	Reference Clock inverted input, AC coupled on the host board – Not required	3
26		GND	Module Ground	1
27		GND	Module Ground	1
28	CML-I	TD-	Transmitter inverted data input	
29	CML-I	TD+	Transmitter non-inverted data input	
30		GND	Module Ground	1



#### Notes:

1. Module circuit ground is isolated from module chassis ground within the module.

2. Open collector, should be pulled up with 4.7k – 10k ohms on host board to a voltage between 3.15Vand 3.6V.

3. A Reference Clock input is not required.